

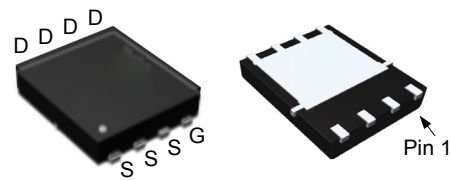
Features

- 40V/48A
 $R_{DS(ON)} = 5.5\text{m}\Omega(\text{typ.}) @ V_{GS} = 10\text{V}$
 $R_{DS(ON)} = 7.5\text{m}\Omega(\text{typ.}) @ V_{GS} = 4.5\text{V}$
- 100% UIS + R_g Tested
- Reliable and Rugged
- Lead Free and Green Devices Available
 (RoHS Compliant)
- Moisture Sensitivity Level MSL1
 (per JEDEC J-STD-020D)

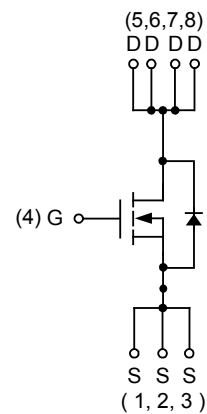
Applications

- Power Management in Desktop Computer or DC/DC Converters.

Pin Description



DFN5x6A-8_EP



N-Channel MOSFET

Absolute Maximum Ratings ($T_A=25^{\circ}\text{C}$ Unless Otherwise Noted)

Symbol	Parameter		Rating	Unit
Common Ratings				
V _{DSS}	Drain-Source Voltage		40	V
V _{GSS}	Gate-Source Voltage		±20	
T _J	Maximum Junction Temperature		175	°C
T _{STG}	Storage Temperature Range		-55 to 175	°C
I _S	Diode Continuous Forward Current	T _C =25°C	60	A
I _D	Continuous Drain Current	T _C =25°C	60	A
		T _C =100°C	38	
I _{DM}	Pulse Drain Current	T _C =25°C	180	A
P _D	Maximum Power Dissipation	T _C =25°C	36	W
		T _C =100°C	17.8	
R _{θJC}	Thermal Resistance-Junction to Case	Steady State	4.2	°C/W
I _D	Continuous Drain Current	T _A =25°C	12.2	A
		T _A =70°C	10.3	
I _{DM} ^a	Pulse Drain Current	T _A =25°C	51	A
P _D ^b	Maximum Power Dissipation	T _A =25°C	2.3	W
		T _A =70°C	1.6	
R _{θJA} ^b	Thermal Resistance-Junction to Ambient	t ≤ 10s	25	°C/W
		Steady State	64	
I _{AS} ^c	Avalanche Current, Single pulse	L=0.1mH	50	A
E _{AS} ^c	Avalanche Energy, Single pulse	L=0.1mH	125	mJ

Note a : Pulse width is limited by max. junction temperature.

Note b : Surface mounted on 1in^2 pad area, steady state $t = 999\text{s}$.

Note c : UIS tested and pulse width limited by maximum junction temperature 175°C (initial temperature $T_J=25^{\circ}\text{C}$).

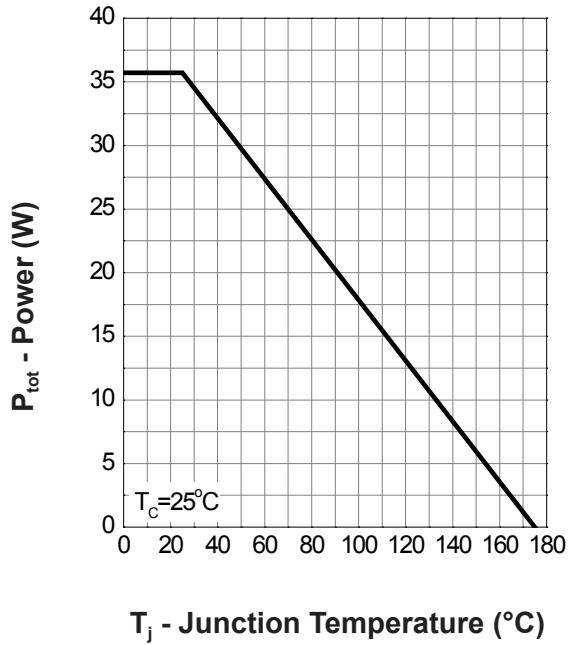
Electrical Characteristics ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _{DS} =250μA	40	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =32V, V _{GS} =0V T _J =85°C	-	-	1 30	μA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _{DS} =250μA	1.0	1.6	2.2	V
I _{GSS}	Gate Leakage Current	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA
R _{DS(ON)} ^d	Drain-Source On-state Resistance	V _{GS} =10V, I _{DS} =20A T _J =125°C	-	5.5 9.4	7.5 -	mΩ
		V _{GS} =4.5V, I _{DS} =15A	-	7.5	11.5	
Gfs	Forward Transconductance	V _{DS} =5V, I _{DS} =15A	-	20	-	S
Diode Characteristics						
V _{SD} ^d	Diode Forward Voltage	I _{SD} =25A, V _{GS} =0V	-	0.85	1.1	V
t _{rr}	Reverse Recovery Time	I _{DS} =20A, dI _{SD} /dt=100A/μs	-	20.2	-	ns
t _a	Charge Time		-	10.4	-	
t _b	Discharge Time		-	8.8	-	
Q _{rr}	Reverse Recovery Charge		-	9.4	-	nC
Dynamic Characteristics						
R _G	Gate Resistance	V _{GS} =0V,V _{DS} =0V,F=1MHz	-	1.6	3.2	Ω
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =20V, Frequency=1.0MHz	-	837	-	pF
C _{oss}	Output Capacitance		-	325	-	
C _{rss}	Reverse Transfer Capacitance		-	12	-	
t _{d(ON)}	Turn-on Delay Time	V _{DD} =20V, R _L =20Ω, I _{DS} =1A, V _{GEN} =10V, R _G =6Ω	-	8.2	15	ns
t _r	Turn-on Rise Time		-	7.3	14	
t _{d(OFF)}	Turn-off Delay Time		-	20.6	38	
t _f	Turn-off Fall Time		-	12.2	22	
Gate Charge Characteristics						
Q _g	Total Gate Charge	V _{DS} =20V, V _{GS} =10V, I _{DS} =20A	-	13.5	-	nC
Q _{gth}	Threshold Gate Charge		-	1.5	-	
Q _{gs}	Gate-Source Charge		-	2.4	-	
Q _{gd}	Gate-Drain Charge		-	2.6	-	

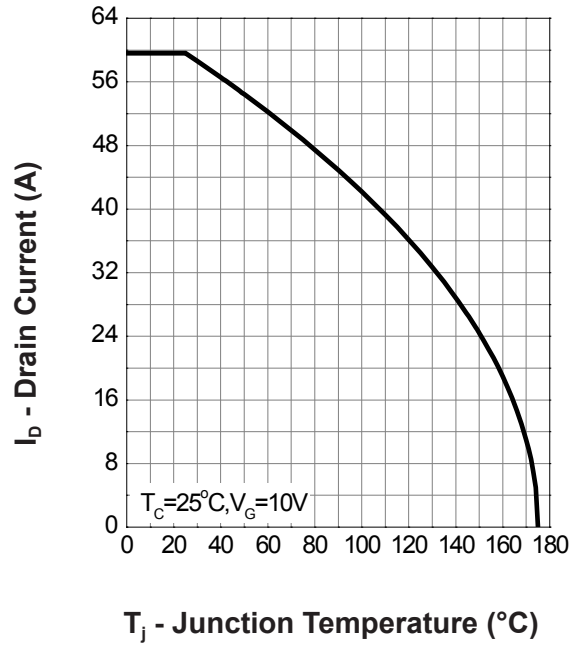
Note d : Pulse test ; pulse width $\leq 300ms$, duty cycle $\leq 2\%$.

Typical Operating Characteristics

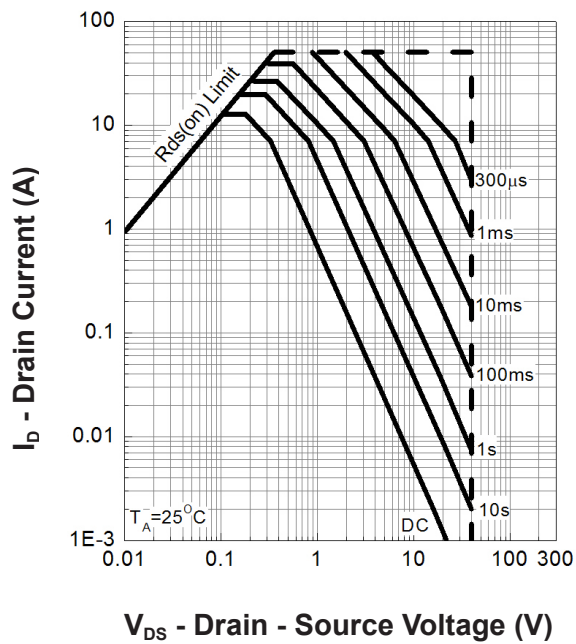
Power Dissipation



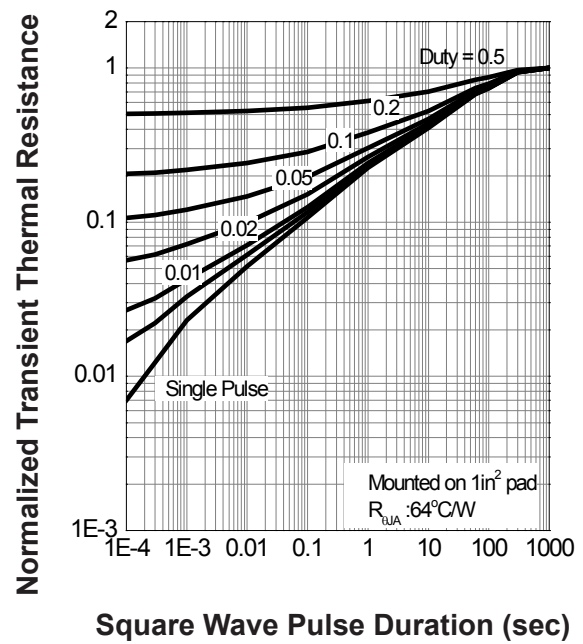
Drain Current



Safe Operation Area

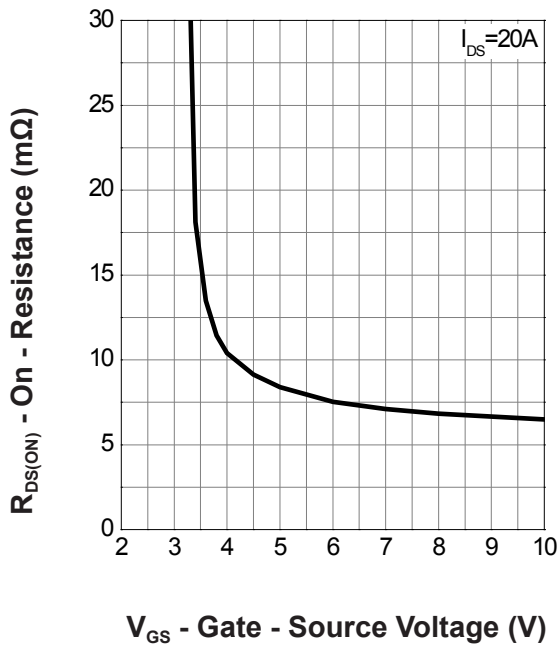


Thermal Transient Impedance

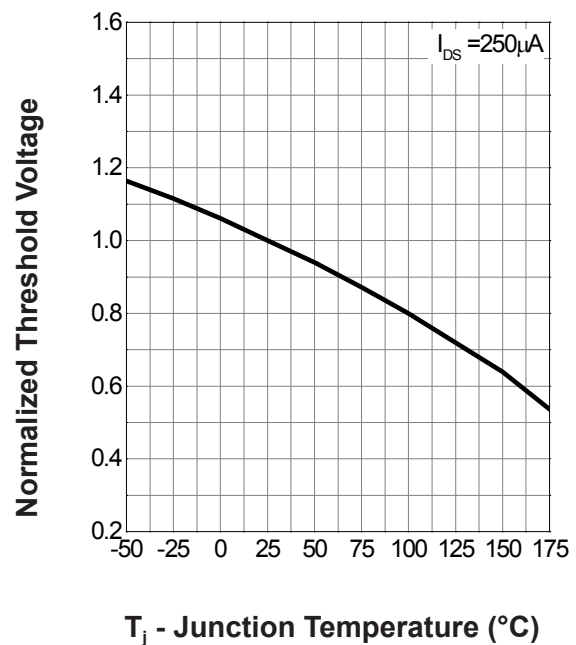


Typical Operating Characteristics(Cont.)

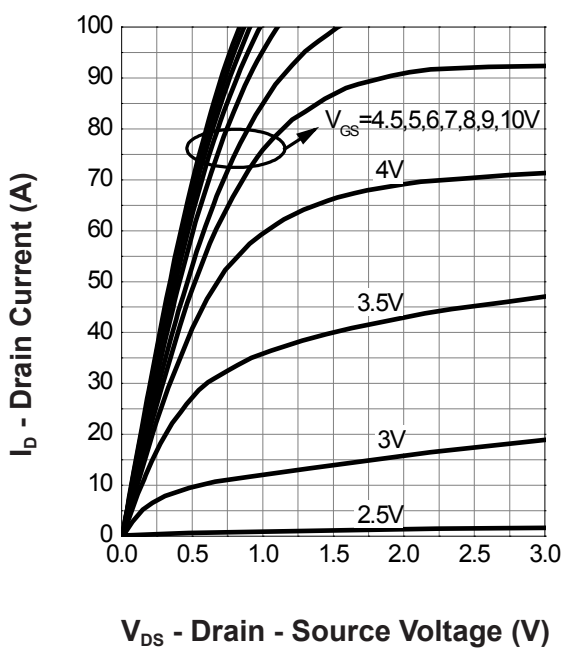
Gate-Source On Resistance



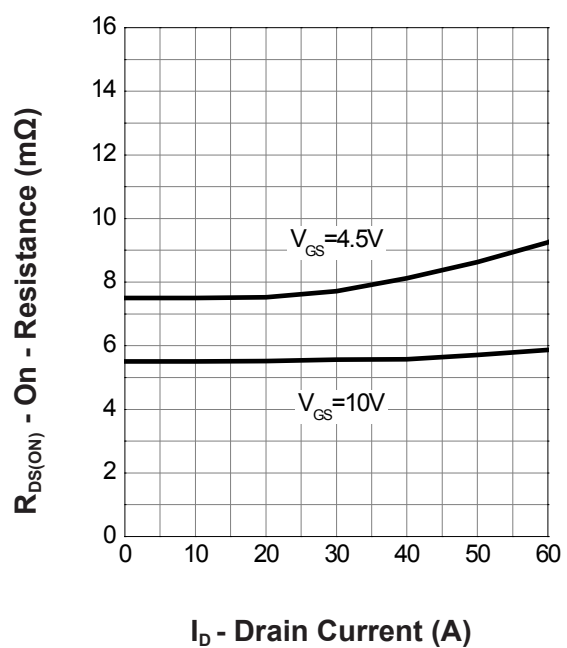
Gate Threshold Voltage



Output Characteristics

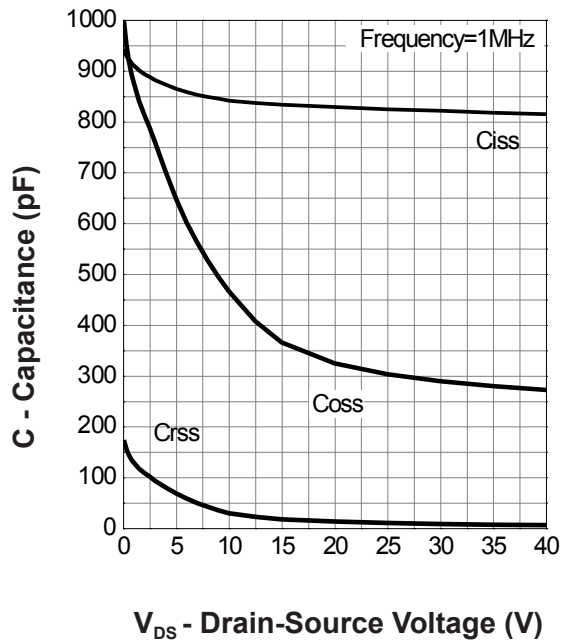


Drain-Source On Resistance

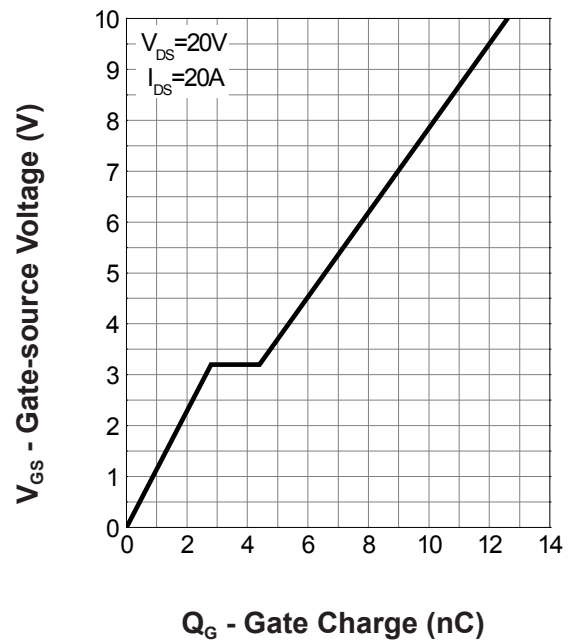


Typical Operating Characteristics(Cont.)

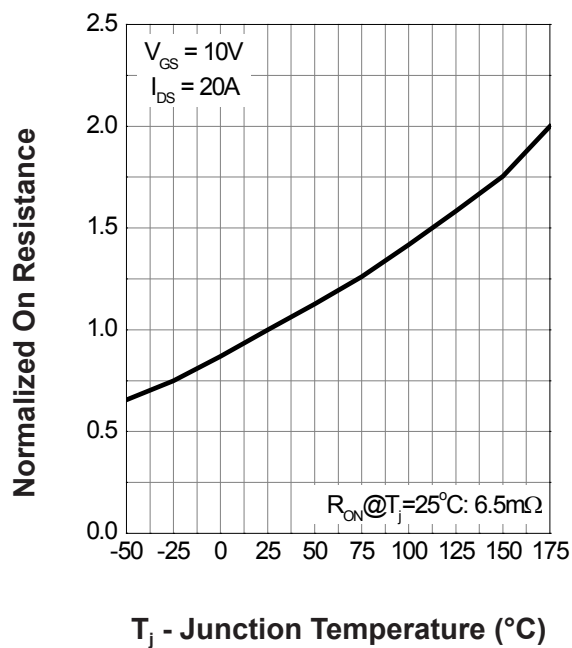
Capacitance



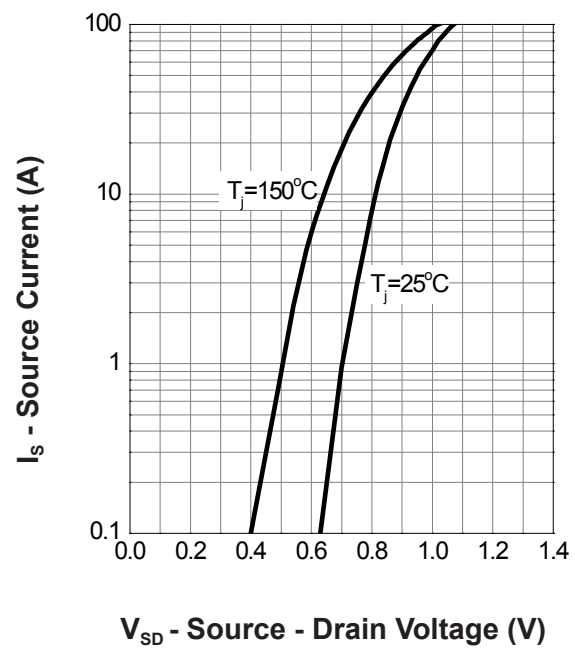
Gate Charge



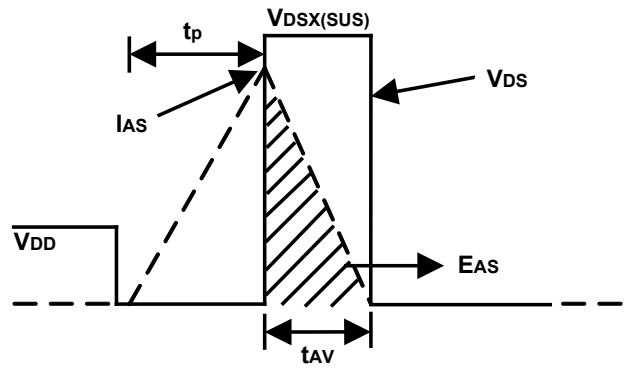
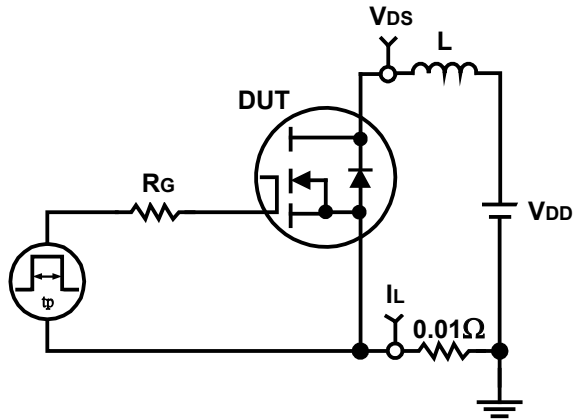
Drain-Source On Resistance



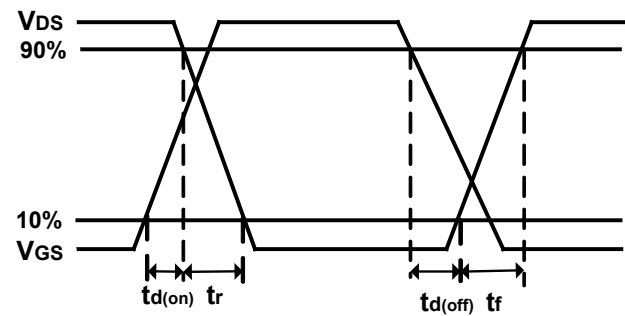
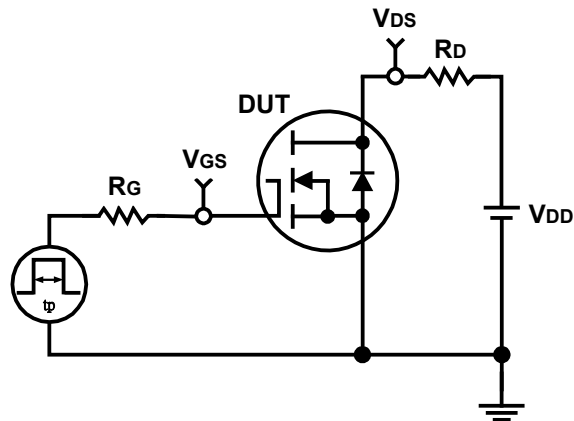
Source-Drain Diode Forward



Avalanche Test Circuit and Waveforms

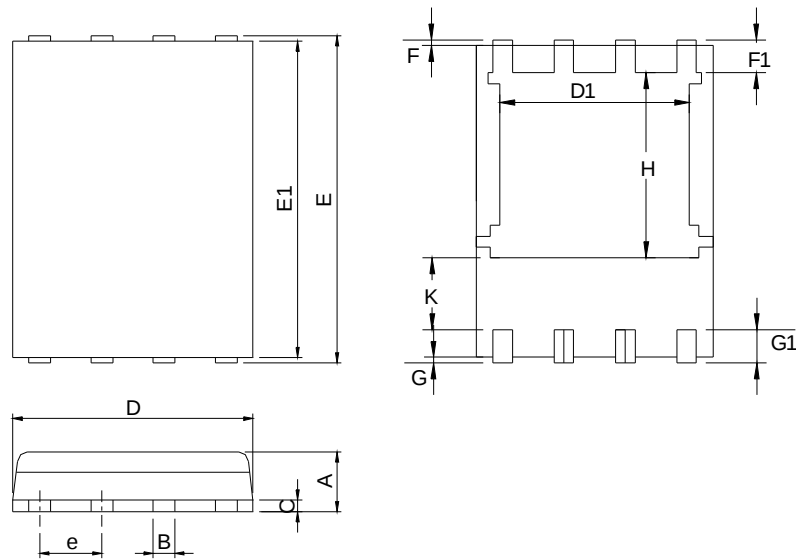


Switching Time Test Circuit and Waveforms



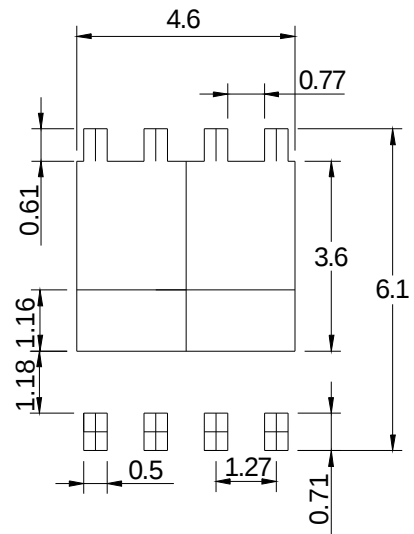
Package Information

DFN5x6-8



SYMBOL	DFN5x6-8			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	0.90	1.20	0.035	0.047
B	0.3	0.51	0.012	0.020
C	0.19	0.25	0.007	0.010
D	4.80	5.30	0.189	0.209
D1	4.00	4.40	0.157	0.173
E	5.90	6.20	0.232	0.244
E1	5.50	5.80	0.217	0.228
e	1.27 BSC		0.050 BSC	
F	0.05	0.30	0.002	0.012
F1	0.35	0.75	0.014	0.030
G	0.05	0.30	0.002	0.012
G1	0.35	0.75	0.014	0.030
H	3.34	3.9	0.131	0.154
K	0.762	-	0.03	-

RECOMMENDED LAND PATTERN



UNIT: mm

Note : 1.Dimension D, D1,D2 and E1 do not include mold flash or protrusions.
Mold flash or protrusions shall not exceed 10 mil.